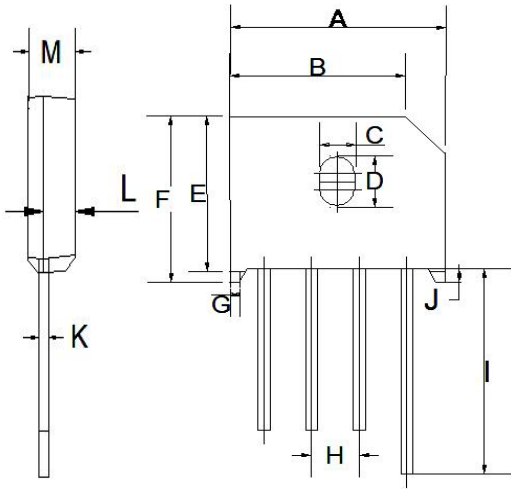


| 特征/Features | 外形尺寸/Outline Dimensions | | | |
|--|--|----|---------|---------|
| <ul style="list-style-type: none"> ◆ GPP芯片 Glass passivated chip ◆ 低反向漏电流 Low Reverse Leakage Current ◆ 高耐浪涌电流能力 High surge current capability ◆ 接线端与壳体间绝缘耐压2500V Case to Terminal Isolation Voltage 2500V | Case: KBU Series Dimensions in millimeters  | 序号 | Min(mm) | MAX(mm) |
| | | A | 22.7 | 23.3 |
| 机械参数/Mechanical Data <ul style="list-style-type: none"> ◆ 本体: 塑封 Case: plastic package ◆ 标识/极性: 本体标记 Marking / Polarity: Marked on Body ◆ 重量: 约克 Weight: About 6.66 rams | | B | 18 | 18.6 |
| | | C | 3.6 | 3.9 |
| | | D | 5.7 | 5.9 |
| | | E | 17.2 | 17.8 |
| | | F | 18.7 | 19.3 |
| | | G | 0.8 | 1.2 |
| | | H | 4.9 | 5.4 |
| | | I | 24.9 | 25.5 |
| | | J | 1.3 | 1.7 |
| | | K | 1.2 | 1.3 |
| | | L | 4.6 | 4.9 |
| | | M | 6.6 | 6.9 |

极限值/Maximum Ratings and Thermal Characteristics @ Ta = 25°C unless otherwise noted

| 符号 Symbol | 特性 Characteristic | KBU4 | | | | | | | 单位 Unit |
|-----------------------------------|---|---------|-----|-----|-----|-----|-----|------|------------------|
| | | 005 | 01 | 02 | 04 | 06 | 08 | 10 | |
| V _{RRM} | 最大反向重复峰值电压 Maximum Recurrent Peak Reverse Voltage | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| I _{F(AV)} | 平均整流输出电流 Average Forward Output Rectified Current@Ta=120°C | 4 | | | | | | | A |
| V _F | 正向峰值电压 Forward Voltage Per Leg @I _{FM} =4.0A | 0.98 | | | | | | | V |
| I _{FSM} | 正向浪涌电流 Peak Forward Surge Current 8.3ms Single Half Sine-wave superimposed on rated load | 160 | | | | | | | A |
| I _R | 反向漏电流 Maximum DC reverse current at rated DC blocking voltage per leg | | | | 5 | 500 | | | uA |
| i ² t | 热容值 Rating for fusing (t<8.3ms) | 106 | | | | | | | A ² S |
| V _{isol} | 绝缘耐压 Rms isolation voltage from case to leads | 2500 | | | | | | | V |
| C _J | 典型结电容 Typical Junction Capacitance | 42 | | | | | | | pF |
| R _{θJC} | 热阻 Maximum thermal resistance per leg | 4.2 | | | | | | | °C/W |
| T _j , T _{STG} | 结温, 存储条件 Operating Junction and storage temperature range | -55~150 | | | | | | | °C |

Note:
 (1) Junction to case with heatsink
 (2) Recommended mounting position is to bolt down on heatsink with silicone thermal compound for maximum heat transfer with M3 screw .

◆ 特性曲线 (典型) Characteristics(Typical)

Fig 1-forwardCurrent derating Curve
图1正向电流降额曲线

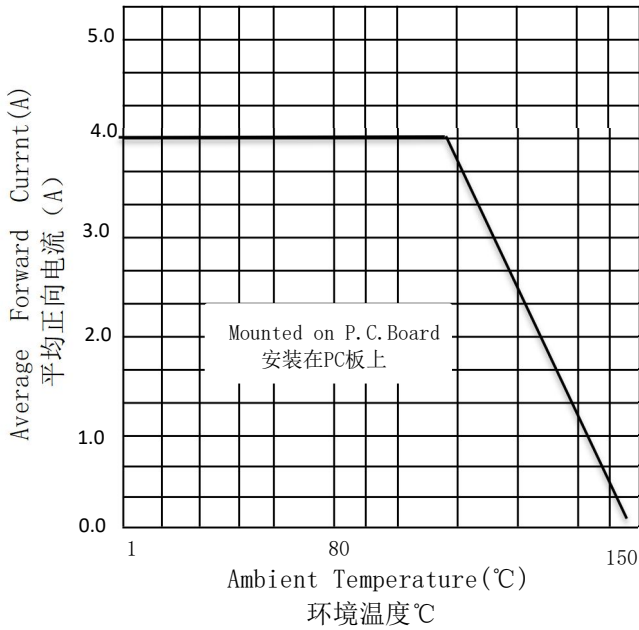


Fig.2-Maximum Non-Repetitive Surge Current
图2 最大不重复正向浪涌曲线

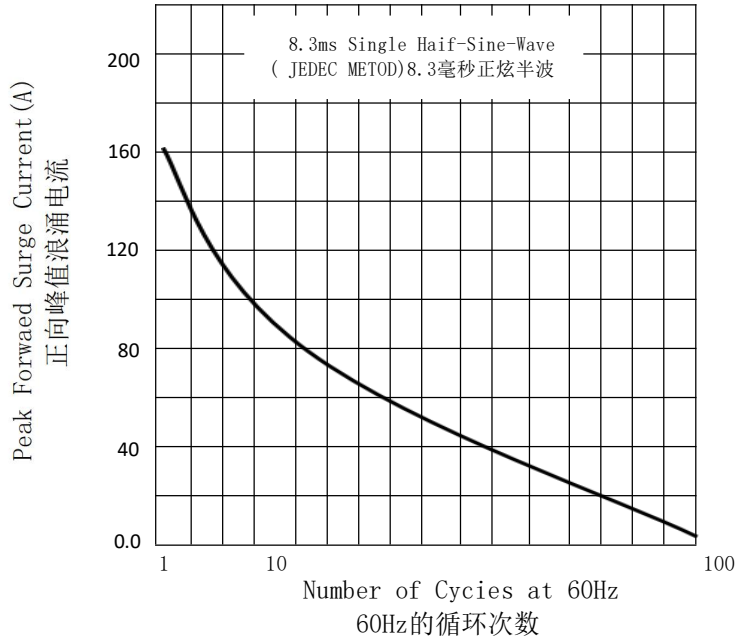


Fig.3-Typical Reverse Characteristics
图3. 典型的反向特性

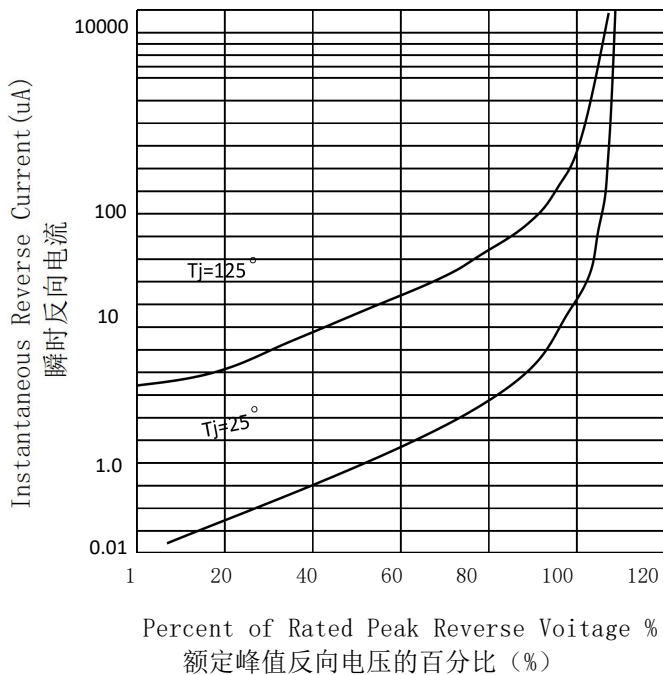


Fig.4-Typical Forward Characteristics
图4. 典型的正向特性

